



503.43552X00

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: SHIBATA et al

Serial No.: 10/797,003

Filed: March 11, 2004

For: Mold Die And Method For Manufacturing Semiconductor
Device Using The Same

Art Unit: 2814

Examiner: Chambliss, A.

AMENDMENT AFTER FINAL REJECTION UNDER 37 CFR 1.116

Mail Stop: AF
Commissioner For Patents
P.O. Box 1450
Alexandria, VA 22313-1450

November 7, 2006

Sir:

This is in response to the Office Action mailed August 7, 2006, in connection with the above-identified application. The amendments are listed below and set forth on the following pages.

Amendments to the Claims;

Amendments to the Drawings; and

Remarks are included following the amendments.

*Do not enter
this amendment
AC
11/28/06*